



Smart Manufacturing Systems for Industry 5.0: Challenges and Opportunities

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Message from the Guest Editors

Dear Colleagues,

In recent years, the focus on smart manufacturing systems has been pushing companies toward a new variety of highly specific technical solutions. These solutions are characterized by an integrated approach to manufacturing termed “digital manufacturing”. There are many different tooling processes that digital manufacturing utilizes, such as artificial intelligence, automation and robotics, additive technology, and human–machine interaction. These tools are unleashing innovations that will change the nature of manufacturing itself.

This Special Issue is will collect a high-quality selection of contemporary research articles on the topic of “Smart Manufacturing Systems for Industry 5.0: Challenges and Opportunities”.

We are particularly interested in publishing articles not only from a traditional point of view but also from new emerging trends in order to meet practitioners’ needs and make theoretical contributions. This call is also aimed at collecting contributions that explore policies and practices adopted in different countries/regions in the field of smart manufacturing, as well as on the results obtained.





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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal *Applied Sciences* has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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